

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
RESUBMIT DOCUMENT ID:	506077344
CONVEYING PARTY DATA	
Name	Execution Date
RAJENDRA D. PENDSE	02/26/2013
RECEIVING PARTY DATA	
Name:	STATS CHIPPAK PTE. LTD. FORMERLY STATS CHIPPAK, LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15827478
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES
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Address Line 4:	CHANDLER, ARIZONA 85248
ATTORNEY DOCKET NUMBER:	2515.0398 CON
NAME OF SUBMITTER:	MARITZA O'NEILL
SIGNATURE:	/MARITZA O'NEILL/
DATE SIGNED:	07/09/2020
Total Attachments: 2	
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source=ASSIGNMENT#page2.tif	

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, RAJENDRA D. PENDSE of Fremont, California, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled THIN 3D FAN-OUT EMBEDDED WAFER LEVEL PACKAGE (EWLB) FOR APPLICATION PROCESSOR AND MEMORY INTEGRATION, which is described, illustrated, and claimed in U.S. Application No. 13/771,825, filed February 20, 2013 and in U.S. Provisional Application No. 61/608,402, filed March 8, 2012, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


Signature for RAJENDRA D. PENDSE

STATE OF CALIFORNIA ; See Attached
COUNTY OF _____

I, _____, a Notary Public in and for the County and State sforesaid, do hereby certify that RAJENDRA D. PENDSE, whose name is subscribed to the foregoing instrument, appeared before me this day in person and acknowledged that he/she signed, sealed and delivered the instrument as his/her free and voluntary act and deed for the uses and purposes therein set forth.

Given under my hand and notarial seal this _____ day of _____, 2013.

CALIFORNIA ALL-PURPOSE ACKNOWLEDGMENT

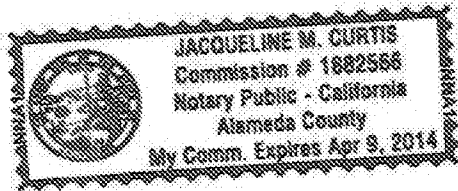
State of California

County of Alameda

On 26 Feb 2013 before me, Jacqueline M. Curtis, Notary Public

personally appeared Rajendra D. Pendse

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.



I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature: Jacqueline M. Curtis
Signature of Notary Public

Place Notary Seal and/or Stamp Above

OPTIONAL

Though the information below is not required by law, it may prove valuable to persons relying on the document and could prevent fraudulent removal and reattachment of this form to another document.

Description of Attached Document

Title or Type of Document: Patent Assignment + Agreement

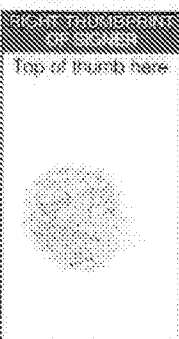
Document Date: 26 February 2013 Number of Pages: 4

Signer(s) Other Than Named Above: None

Capacity(ies) Claimed by Signer(s)

Signer's Name: Rajendra D. Pendse

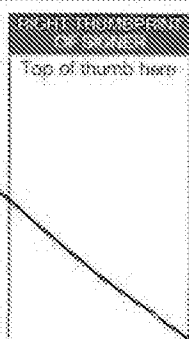
- Corporate Officer — Title(s): _____
- Individual
- Partner — Limited General
- Attorney in Fact
- Trustee
- Guardian or Conservator
- Other: _____



Signer is Representing: _____

Signer's Name: _____

- Corporate Officer — Title(s): _____
- Individual
- Partner — Limited General
- Attorney in Fact
- Trustee
- Guardian or Conservator
- Other: _____



Signer is Representing: _____